

BPC-5112

Fanless Compact Embedded Box PC with 14th/13th/12th Intel® Core™ LGA 1700 Processor

Applications

- Edge AI Computing
- Factory Automation
- Motion Control
- Machine Vision
- Data Analytics

Features

- Supports 14th/13th/12th Gen Intel® Core™ LGA 1700 CPU
- Dual Channel DDR5 4800/5600MHz, up to 96GB
- Multiple Display: 2 x HDMI 2.0b, 1 x DP 1.4a++
- 1 x 2.5GbE, 1 x 1.0GbE
- Supports GPIO: 4 x Input & 4 Output
- 12~28VDC Input
- -20°C ~ 60°C Wide Operating Temperature



Ordering Information

Part No.	Description
BPC-5112-1A1	14th/13th/12th Gen Intel® Core™ LGA1700 CPU, Q670 Chipset, 1 x 2.5GbE, 1 x 1.0GbE, 2 x HDMI, 1 x DP, 2 x RS232/422/485, 4 x USB3.2, 4 x USB2.0, GPIO, Mic-In/Line-Out, 12~28VDC

Packing List

Description

1 x BPC-5112-1A1

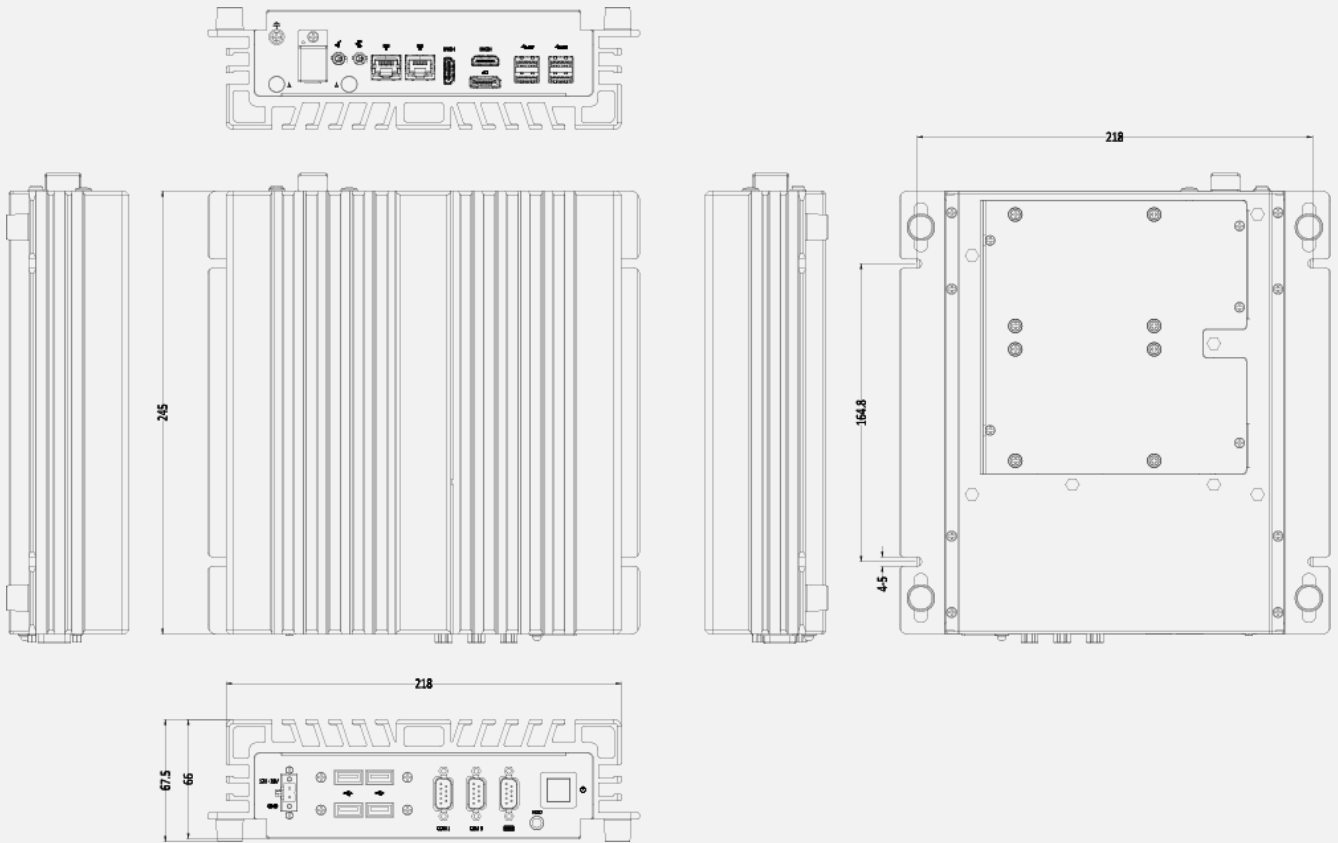
Optional Items

Part No.	Description
EA-PS-120W24VTB2x-0111	120W/24V/5A_ -30~70°C_TB2_GST120A24-AV
27-x301010005-CA	Power Cord, 3-pin EU Type, 180 cm
27-x301000003-CA	Power Cord, 3-pin US Type, 180 cm
i7-14700T	14 th Gen Intel® Core™ i7-14700T Raptor Lake Refresh_30M Cache, up to 5.00GHz_35W
i5-14500T	14 th Gen Intel® Core™ i5-14500T Raptor Lake Refresh_24M Cache, up to 4.80GHz_35W
i3-14100T	14 th Gen Intel® Core™ i3-14100T Raptor Lake Refresh_12M Cache, up to 4.40GHz_35W
i7-13700TE	13 th Gen Intel® Core™ i7-13700TE Embedded_Raptor Lake_30M Cache, up to 4.80GHz_35W
i5-13500TE	13 th Gen Intel® Core™ i5-13500TE Embedded_Raptor Lake_24M Cache, up to 4.50GHz_35W
i3-13100TE	13 th Gen Intel® Core™ i3-13100TE Embedded_Raptor Lake_12M Cache, up to 4.10GHz_35W
i7-12700TE	12 th Gen Intel® Core™ i7-12700TE Embedded_Alder Lake_25M Cache, up to 4.60 GHz_35W
i5-12500TE	12 th Gen Intel® Core™ i5-12500TE Embedded_Alder Lake_18M Cache, up to 4.30 GHz_35W
i3-12100TE	12 th Gen Intel® Core™ i3-12100TE Embedded_Alder Lake_12M Cache, up to 4.00 GHz_35W
AWD-4G003	4G (LTE) EG25-G + 2 Antennas, Full Size (for Global)
AWD-WF003	Wi-Fi 802.11 a/b/g/n/ac/BT4.0 (2T2R) + 2 Antennas (Dual Band), Half Size
AWD-WF005	Wi-Fi 802.11 a/b/g/n/ac/BT4.0 (2T2R) +2 Antennas (Dual Band), M.2 2230 Type

Specifications

Model		BPC-5112-1A1
Processor System	CPU	14 th /13 th /12 th Intel® Core™/Pentium®/Celeron® 35W LGA 1700 Processors
	System Chipset	Intel® Q670
	BIOS	AMI 256 Mbit
	TPM	TPM 2.0 onboard IC
Memory	Technology	Dual Channel DDR5 4800/5600MHz
	Max. Capacity	96GB
	Socket Type	2 x 262-pin SO-DIMM
Display	Graphics Engine	Intel® UHD Graphics
	Multiple Display	3
	HDMI	2 x HDMI 2.0b, Max resolution up to 4096x2160
	DP	1 x DP, Max solution 4096 x 2160
I/O Interface	USB	4 x USB3.2, 4 x USB2.0
	Serial Port	2 x RS232/422/485
	Ethernet	1 x 2.5GbE Intel® i226V
		1 x 1.0GbE Intel® i219-LM
	Audio	1 x Line-out, 1 x Mic-in (Realtek ALC897 HD)
	GPIO	4 x Input, 4 x Output (D-SUB 9-pin)
	Antenna Hole	2
Storage	2.5" HDD / SSD	2 x Internal 2.5" HDD SATA III (6.0 Gb/s)
	M.2	1 x M.2 M-Key 2242/2280 (PCIe Gen4 x4 and SATA III)
		1 x M.2 M-Key 2242 (PCIe Gen4 x4 and SATA III)
RAID	Intel® VMD RAID 0/1	
Expansion	M.2	1 x M.2 E-Key 2230 (PCIe x1, USB 2.0 and CNVi for Wireless) 1 x M.2 B-Key 3042/3052 (PCIe x1, USB 3.2 Gen1, and USB 2.0)
Power	Power Mode	AT / ATX
	Power Supply Voltage	12~28VDC Input
	Power Connector Type	1 x 2-pin Terminal Block Connector
Mounting	Type	Wall Mount
Environment	Operating Temperature	-20 ~ 60°C
	Storage Temperature	-40 ~ 75°C
	Humidity	5% ~ 90% (Non-condensing)
	Vibration	1Grms, 5-500 Hz, 1hr/Axis
	Shock	20Grms, Half-sine 11ms
General	Certification	CE/FCC Class A
	Thermal Dissipation	Fanless System
	Material	Extruded Aluminum
	Dimensions (W x D x H)	238 x 245 x 66mm
	Net Weight	3.22kg
	Operating System	Windows 10 IoT, Windows 11 (IoT/Professional), Linux

Dimensions



Viewing

